125 Series Wi**125**



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Revision History of Version 1.0

Revision	Date	Released By	Note
00	07/20/09	Keith Loiselle	New Release of Wi125 Data Sheet
01	04/13/10	Dave Jahr	Update to 1PPS (timing) Accuracy Specification
02	06/16/10	Dave Jahr	125 Series Revised

Table 1 Revision History

Other Documentation

The following additional documentation may be of use in understanding this document.

Document	Ву	Note
Wi125 User Manual	Connor-Winfield	
Wi125 Dev Kit User Manual	Connor-Winfield	

Table 2 Additional Documentation List



1 INTRODUCTION

The 125 Series Wi125 is a small OEM surface mount GPS module specifically designed for use in synchronization and timing in WiMax applications. This compact module has an onboard programmable NCO oscillator that outputs a synthesized frequency up to 30 MHz that is steered by a GPS receiver. The self-survey mode of operation allows the receiver to enter a position hold mode allowing accurate timing to be continued with only one satellite being tracked.

Additionally, the 125 Series Wi125 has phase alignment of 1 PPS/10 MHz with a very stable holdover. The 1 PPS/10 MHz outputs maintain phase alignment with holdover being base only on the local oscillator, dismissing spurious GPS measurements during reacquisition. When the receiver regains GPS lock after a period of holdover, the 1PPS and 10 MHz outputs maintain phase alignment and are offset in frequency at the maximum rate of 100 ppb until the 1 PPS aligns with that of the GPS solution. This slow recovery from holdover allows for uninterrupted operation of the WiMax base station.

The Wi125 has a highly accurate output frequency, which can achieve full PRC MTIE performance. Additionally it can track satellites and provide GPS synchronization in weak signal areas including indoor applications, reducing the need for high antenna placement.

The Wi125 is an exceptionally small surface mount package with a highly integrated architecture that requires a minimum of external components allowing easy integration into host systems.

Key information includes:

- System Block Diagram
- Maximum Ratings
- Physical Characteristics Wi125 Dimensions, castellation information Solder Pad and placement information
- Signal Descriptions
- Special Features
- Application Information

Power supply modes

RF connections

Grounding

Battery Back-up

Over Voltage and Reverse Polarity

LED's

Features

- 1PPS/ 10 MHz Phase alignment
- Stable Holdover
- Holdover Recovery
- 1 PPS & NCO Frequency Output
- GPS/UTC time/scale synchronization to 25 ns RMS
- Stable proven design with long term availability and multi-year support
- 12 channel hardware correlator processor design
- OEM SM footprint 25 x 27 mm
- Automatic entry into holdover
- Loss-of-lock and entry-into-holdover indication

The specifications in the following sections refer to the standard software builds of the Wi125. The performance and specification of the Wi125 can be modified with the use of customized software builds.



2 SPECIFICATION ¹

2.1 Performance

Physical	Module dimensions	25mm (D) x 27mm (W) x 4.2mm (H)
. Hyolodi	Supply voltages	3V3 (Digital I/O), 3V3 (RF), 1V8 (Core option), 3V
	11,7	(Standby Battery)
	Operating Temp	-30°C to +85°C
	Storage Temp	-40°C to +85°C ²
	Humidity	5% to 95% non-condensing
	Max Velocity / Altitude	515ms ⁻¹ / 18,000m
	Max Acceleration / Jerk	4g / 1gs ⁻¹ (sustained for less than 5 seconds)
Sensitivity	Acquisition w/network assist	-185dBW
	Tracking	-186dBW
	Acquisition Stand Alone	-173dBW
Acquisition	Hot Start with network assist	Outdoor: <2s
Time		Indoor (-178dBW): <5s
	Stand Alone (Outdoor)	Cold: <45s
		Warm: <38s
		Hot: <5s
		Reacquisition: <0.5s (90% confidence)
Accuracy	Position: Outdoor / Indoor	<5m rms / <50m rms
	Velocity	<0.05ms ⁻¹
	Latency	<200ms
	Raw Measurement Accuracy	Pseudorange <0.3m rms, Carrier phase <5mm rms
	Tracking	Code and carrier coherent
Power	1 fix per second	0.6W typically
	Coma Mode Current	10mA
	(RF3V3+DIG 3V3)	
	Standby Current (VBATT)	1.5μΑ
Interfaces	Serial	3 UART ports, CMOS levels
	Multi-function I/O	1PPS and Frequency Output available on GPIO [0]
		Event Counter/Timer Input
		Up to 4 x GPIO (multi-function)
		2 x LED Status Drive
		I ² C, External Clock (on special build)
	Protocols	Network Assist, NMEA 0183, Proprietary ASCII and
		binary message formats
	1pps Timing Output	10nS rms accuracy, <5nS resolution
		User selectable pulse width
	Event Input	30nS rms accuracy, <10nS resolution
	Frequency Output (GPIO [0])	10 Hz to 30 MHz (Wi125)
	Receiver Type	12 parallel channel x 32 taps up to 32 point FFT.
		Channels, taps and FFT can be switched off to
		minimize power or simulate simpler designs.
General	Processor	ARM 966E-S on a 0.18µ process at up to 120 MHz.

Note: 1. The features listed above may require specific software builds and may not all be available in the initial release.

Table 3 Wi125 Specification



^{2.} Please contact factory for other temperature options.

2 SPECIFICATION continued

2.2 Recommended Ratings

Symbol	Parameter	Min	Max	Units	
RF_3V3	RF Supply Voltage	+3.0	+3.6	Volts	
DIG_3V3	Digital Supply Voltage	+3.0	+3.6	Volts	
DIG_1V8	Digital Supply Voltage	+1.65	+1.95	Volts	
VBATT	Battery Backup Voltage	+2.7	+3.5	Volts	
ANT_SUPPLY	Antenna Supply Voltage	+3.0	+12	Volts	

Table 4 Recommended Maximum Ratings

2.3 Absolute Maximum Ratings

Symbol	Parameter	Min	Max	Units	
RF_3V3	RF Supply Voltage	-0.3	+6.5	Volts	
DIG_1V8	Digital Supply Voltage	-0.3	+2.0	Volts	
DIG_3V3	Digital Supply Voltage	-0.3	+3.7	Volts	
VBATT	Battery Backup Voltage	-0.5	+7.0	Volts	
ANT_SUPPLY	Antenna Supply Voltage	-15	+15	Volts	
DIG_SIG_IN	Any Digital Input Signal	-0.3	+5.5	Volts	
RF_IN	RF Input	-15	+15	Volts	
TSTORE	Storage temperature	-40	+85	°C	
IOUT	Digital Signal Output Current	-6	+6	mA	

Table 5 Absolute Maximum Ratings

2.4 Block Diagram

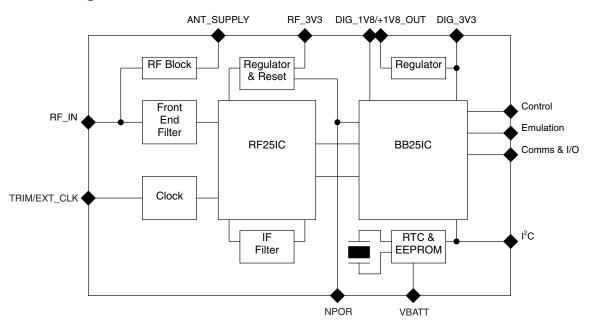


Figure 1 Wi125 Block Diagram



3 PHYSICAL CHARACTERISTICS

The 125 Series Wi125 is a multi-chip module (MCM) built on an FR4 fiberglass PCB. All digital and power connections to the Wi125 are via castellations on the 25 x 27 mm PCB. The RF connection is via castellations or an RF connector. The general arrangement of the Wi125 is shown in the diagram below. Dimensions are in mm (inches/1000).

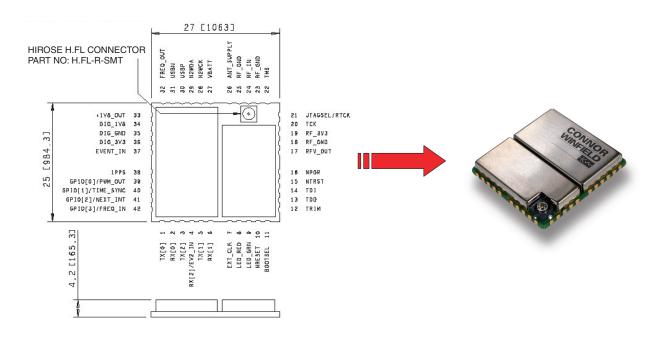


Figure 2 Wi125 Form and Size

3.1 Physical Interface Details

The interface to the Wi125 is via 1mm castellations on a 2mm pitch. There are 42 connections in all. There is also an RF connector for connecting to the GPS antenna. The details of the interface connections are given below.

Note: 3. Frequency Output is available on pin 32 (FREQ_OUT) with custom software only.

Table 6 Wi125 Signal List



3 PHYSICAL CHARACTERISTICS continued

3.2 Wi125 Dimensions

The figure below provides the dimensions of the positioning of the Wi125 castellations. Dimensions are in mm (inches/1000).

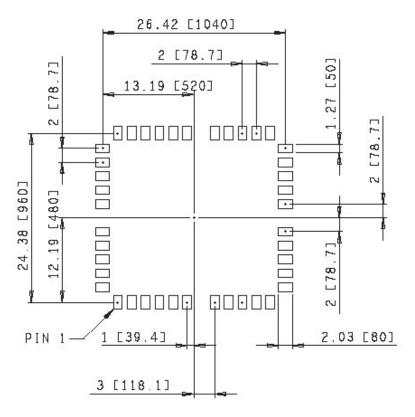


Figure 3 Wi125 Dimensions

3.3 Solder Pad Size and Placement

It is recommended that the footprint of the solder pad under each castellation be 2mm x 1mm, centered on the nominal centre point of the radius of the castellation. The castellations are gold plated and so are lead free. Note that if the RF IN connector is being used, there should not be a pad or solder resist under the RF IN castellation. If the RF_IN castellation is to be used, the pad should be shortened by 0.5mm underneath the Wi125 and standard RF design practices must be observed. The diagram below shows the placement of the pads under the castellations.



Figure 4 Solder Pad Size and Placement



4 SIGNAL DESCRIPTION

The signals on the Wi125 are described in the table below.

4.1 Power Signals

RF_3V3	Type: Power	Direction: Input	Pin: 19
	section of the Wi125		s the 2.9V LDO regulator in the RF is well filtered with no more that
_RF_GND	Type: Power	Direction: Input/Output	Pins: 18, 23, 25
	•	•	RF_3V3 supply and the ground for DIG_GND externally to the Wi125.
RFV_OUT	Type: Power	Direction: Output	Pin: 17
	the power to the RF RF components but	subsystem of the Wi125 . This m	y the RF_3V3 signal. This supplies hay also be used to power external noise onto this signal. No more than external circuitry.
_ANT_SUPPLY	Type: Power	Direction: Input	Pin: 26
		enna. The maximum voltage sho	upply power to the RF_IN signal, for ould not exceed ±15V and the current
DIG_3V3	Type: Power	Direction: Input	Pin: 36
	and the LDO regulate		olies the I/O ring of the BB25IC chip 125 . It is important that this supply is sise with respect to DIG_GND.
DIG_1V8	Type: Power	Direction: Input	Pin: 34
	to the +1V8_OUT sig		nis is normally connected directly V ± 5% is available, a lower overall ng an external supply.
+1V8_OUT	Type: Power	Direction: Output	Pin: 33
	The 1.8V output from this is connected to the but care must be taken	n the LDO regulator that is powe he DIG_1V8 signal. This may al	ered by the DIG_3V3 signal. Normally, so be used to power external logic ignal. No more than an additional
DIG_GND	Type: Power	Direction: Input/Output	Pin: 35
	· ·	•	3V3 supply and the ground reference RF_GND externally to the Wi125.



4.1 Power Signals cont'd

VBATT	Type: Power	Direction: Input/Output	Pin: 27
	powered from the V DIG_3V3) should b The input has a blo ing circuit. Typically	BATT signal. A supply of typic e applied to this signal. This si cking diode and so rechargeal, a 1K resister in series with th	n board Real Time Clock (RTC). This is ally 3v (greater than 2.5V and less than gnal can be left floating if not required. ble batteries will need an external chargis signal and the external battery will consumption from VBATT during test.
4.2 RF Signals			
RF_IN	Type: RF	Direction: Input	Pin: 24
	be used when track ANT_SUPPLY sign Wi125 . Only one a	king to this signal. This signal h al. This is the same signal pres ntenna connection should be r	tenna. Standard RF design rules must has an RF blocked connection to the sented on the RF connector on the made. If the RF connector is to be used, connected pad, to this castellation.
TRIM	Type: RF	Direction: Input	Pin: 12
	When floating, this jected into this sign	signal is biased to the control	CXO. This signal is normally left open. voltage of the VCTCXO. Any noise inee performance of the Wi125. This signal pplication notes.
EXT_CLK	Type: RF	Direction: Input	Pin: 7
	the Wi125 that are the VCTCXO, do no	not fitted with an internal VCT0 ot connect this input. The exter or an amplitude between 1V and	s to be used only in special builds of CXO. For the normal build, containing rnal clock is a 9 MHz to 26 MHz clipped d 3V peak to peak. The return path for
4.3 Emulation/Te	est Signals		
TDI	Type: Test	Direction: Input	Pin: 14
	The Test Data In Si is DIG_GND.	gnal. This is the standard JTAC	G test data input. The signal return path
TDO	Type: Test	Direction: Output	Pin: 13
	The Test Data Out spath is DIG_GND.	Signal. This is the standard JT/	AG test data output. The signal return
TCK	Type: Test	Direction: Input	Pin: 20
			test clock input. The signal return path is



4.3 Power Signals cont'd

TMS	Type: Test	Direction: Input	Pin: 22
	The Test Mode Sepath is DIG_GND.	lect Signal. This is the standard	JTAG test mode input. The signal return
JTAGSEL/RTCK	Type: Test	Direction: Input/Output	Pin: 21
	an input and select the embedded AR mode is selected. When NPOR is de signal provides the a single clock dom cause a variable le nized version of the	ets the function of the JTAG interests the function of the JTAG interests. When the value on this signal is latched asserted (high) and the JTAG of the return clock to the ARM Multiplain, the TCK has to be internally ength delay in the validity of the	ignal is asserted (low), this signal is rface. When high, JTAG emulation into how, the BB25IC chip boundary scan ed when NPOR de-asserts (goes high). emulation mode has been latched, this ICE. Because the ARM9 functions off y synchronized in the ARM9. This can TDO signal. The RTCK is a synchroses the RTCK output signal to indicate the blg_GND.
NTRST	Type: Test	Direction: Input	Pin: 15
4.4 Control Sigi	is DIG_GND.	gnal. This is the active low JTAG	test reset signal. The signal return path
NPOR	Type: Control	Direction: Input/Output	Pin: 16
THI OIT	The Power On Re the Wi125 . The W used to reset exte	set Signal. This active low, open /i125 can be held in reset by ass	collector signal is the master reset for serting this signal. The signal can be aken to ensure no DC current is drawn
NRESET	Type: Control	Direction: Input/Output	Pin: 10
	The System Reset Signal. This active low, open collector signal is generated by the BB25IC chip in response to the assertion of the NPOR. It may also be driven to reset the ARM9 processor in the BB25IC without completely re-initializing the chip.		
BOOTSEL	Type: Control	Direction: Input	Pin: 11
	by the Wi125 . Thi signal is high or le	s signal is sampled when the NI	t up modes, but only two are supported POR is de-asserted. If the BOOTSEL from its on-chip FLASH memory. If the om its on-chip ROM.



4.5 I/O Signals

TX[0]	Type: I/O	Direction: Output	Pin: 1
	The Transmit Signate path is DIG_GND.	al for UART 0. This is a standard	UART output signal. The signal return
TX[1]	Type: I/O	Direction: Output	Pin: 5
	The Transmit Signate path is DIG_GND.	al for UART 1. This is a standard	UART output signal. The signal return
TX[2]	Type: I/O	Direction: Output	Pin: 3
	The Transmit Signal for UART 2. This is a standard UART output signal. The signal return path is DIG_GND.		
RX[0]	Type: I/O	Direction: Input	Pin: 2
	The Receive Signal for UART 0. This is a standard UART input signal. The signal return path is DIG_GND.		
RX[1]	Type: I/O	Direction: Input	Pin: 6
	The Receive Signate path is DIG_GND.	al for UART 1. This is a standard l	JART input signal. The signal return
_RX[2]/EV2_IN	Type: I/O	Direction: Input	Pin: 4
	This is a Dual Mode Signal. Normally, this is the receive signal for UART 2, a standard UART receive signal. Under software control, it can also be used as general purpose I/O or to detect events. It can be used to detect the timing of the leading edge of the start bit of the incoming data stream. The signal return path is DIG_GND.		
FREQ_OUT	Type: I/O	Direction: Input/Output	Pin: 32
	Optional Frequency Output Signal. This is NOT the same signal as pin 39. This signal is turned off by default. This is a complex signal which under software can provide any of either an NCO generated output frequency, a PWM signal, a GPS aligned EPOCH pulse or general purpose I/O signal. The signal return path is DIG_GND.		
1PPS	Type: I/O	Direction: Input/Output	Pin: 38
	The 1 Pulse Per Second Signal. This is normally a 1 pulse aligned with GPS time, bu under software control also provide general purpose I/O or an additional event input. pulse width of the 1PPS is software selectable with a default of 100µs. The signal retroated path is DIG_GND.		
EVENT_IN	Type: I/O	Direction: Input/Output	Pin: 37
	The Event Input Signal with internal connection to Pin 39 (GPIO[1] / Time Sync) allows phase measurement of the Frequency Output. The signal return path is DIG_GND.		



4.5 I/O Signals cont'd

N2WCK	Type: I/O	Direction: Input/Output	Pin: 28
	•		collector I2C compatible Clock Signal
	for the 2 wire serial interface. The signal return path is DIG_GND.		
N2WDA	Type: I/O	Direction: Input/Output	Pin: 29
	The NavSync 2 Wire Data Signal. This is the open collector I2C compatible Data Signal		
	for the 2 wire serial interface. The signal return path is DIG_GND.		
USBP ⁴	Type: I/O	Direction: Input/Output	Pin: 30
	The positive USB Signal. The signal return path is DIG_GND.		
USBN ⁴	Type: I/O	Direction: Input/Output	Pin: 31
	The negative US	B Signal. The signal return path is E	DIG_GND.
LED_RED	Type: I/O	Direction: Output	Pin: 8
	This is a Dual Fu	nction Signal. Normally this signal is	s used to drive a red LED. Standard
		_	s. In special software builds, this sig-
		_	MOS drive. A series limiting resistor is
	required to limit d	output current to ±5mA. The signal r	eturi patri is Did_GND.
LED_GRN	Type: I/O	Direction: Output	Pin: 9
		nction Signal. Normally this signal is	_
	dard software builds use this signal to indicate GPS status. In special software builds, this signal can be used as GPIO. This signal has a 3.3V CMOS drive. A series limiting resistor is required to limit output current to ±5mA. The signal return path is DIG_GND.		
GPIO[0]/PWM	Type: I/O	Direction: Input/Output	Pin: 39
	•		ency Output that defaults to 10 MHz,
		•	al. The output is enabled on power-up
	-	the GPS solution. Custom soπware WM or EPOCH output. The signal r	e versions can also configure this pin
	ior general i/o, i	vvivi or Er Gori Gatpat. The signar	otam patino bia_anb.
GPIO[1]/TIME_SYNC	Type: I/ODirection	n: Input/Output	Pin: 40
	The GPIO[1]/TIME_SYNC pin provides a synchronization pulse generated by the on-		
	board RTC. Custom software versions can also configure this pin for general purpose I/O, or an additional PPS output. The signal return path is DIG_GND.		
Note A HOD's set of the	or an additional F	רא סענput. דחפ signal return path is	S DIG_GND.

Note: 4. USB is not supported in the current software build.



4.5 I/O Signals cont'd

GPIO[2]/NEXT_INT	Type: I/O	Direction: Input/Output	Pin: 41	
			status indicator for the Frequency	
	Output available on pin 39 (GPIO[0]/PWM). Custom software versions can also configure			
	this pin for general purpose I/O. The signal return path is DIG_GND.			
GPIO[3]/FREQ_IN	Type: I/O	Direction: Input/Output	Pin: 42	
	The GPIO[3]/FREQ_IN output provides an active high status 3D fix indicator. This indi-			
	cator can also be used to determine the validity of the pin 38 (1PPS) output. The signal			
	return path is DIG_GND.			

5 SPECIAL FEATURES

While most of the features on the Wi125 are just a subset of the capabilities of the Wi125 and so are described in the Wi125 Data Sheet and the Wi125 User Manual, there are some additional features specific to the Wi125 that require explanation.

5.1 User Commands

The Wi125 can accept a number of specific user commands for setting receiver parameters such as UART baud rate and NMEA message subset, output frequency, etc. Many of these parameters are stored in Non-Volatile Memory (NVM) so that the settings are retained when the receiver loses power. The available commands are defined in detail in the Wi125 User Manual.

5.2 Self Survey

To optimize timing performance, the Wi125 performs a 10-minute survey each time the receiver is powered up and after obtaining a GPS fix. When the survey is complete, the receiver automatically enters fixed timing mode. For applications with specific timing performance requirements, it may be necessary to allow the survey to complete before using the 1PPS and frequency outputs. The status of the survey can be determined by querying the receiver dynamics setting as described in the Wi125 User Manual.

5.3 Wi125 Embedded Identification

The hardware version number is hard coded onto the Wi125; firmware also contains a version number allowing for easy identification of the hardware and software version in embedded applications.



6 TAPE AND REEL SPECIFICATIONS

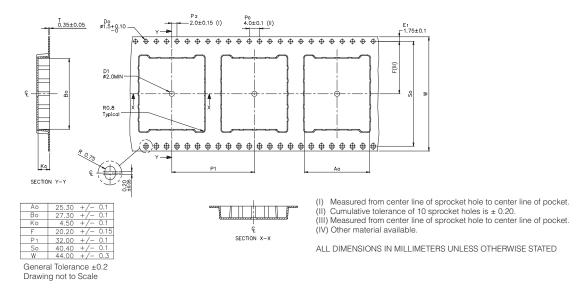


Figure 5 Tape and Reel

7 SOLDER PROFILE

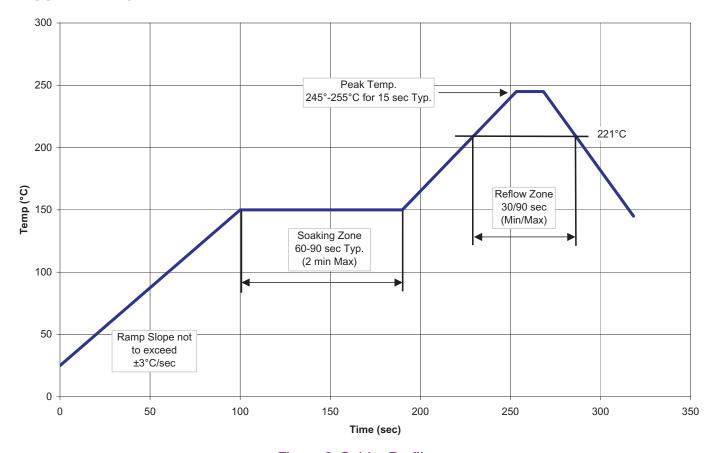


Figure 6 Solder Profile



8 APPLICATION HINTS

The following are a list of application hints that may help in implementing system based on the Wi125.

8.1 Power Supply

The power supply requirements of the Wi125 can all be provided from a single 3.3V supply. To simplify system integration on-board regulators provide the correct voltage levels for the RF and oscillator (2.9V or 3.0V) and low voltage digital core (1.8V). In power sensitive applications it is recommended that the DIG_1V8 supply is provided from a high efficiency external 1.8V source e.g. switch mode power supply, rather than the on-board linear regulator.

If the source impedance of the power supply to the Wi125 is high due to long tracks, filtering or other causes, local decoupling of the supply signals may be necessary. Care should be taken to ensure that the maximum supply ripple at the pins of the Wi125 is 50mV peak to peak.

8.2 RF Connection

The RF connection to the Wi125 can be done in two ways. The preferred method is to use standard microstrip design techniques to track from the antenna element to the RF_IN castellation. This also allows the systems integrator the option of designing in external connectors suitable for the application. The user can easily fit an externally mounted MCX, SMA or similar connector, provided it is placed adjacent to the RF_IN castellation. If the tracking guidelines given below are followed, the impedance match will be acceptable. The diagram below shows how this could be achieved. In this diagram, the centre via of the RF connector is presumed to be plated through with a minimal pad top and bottom. The PCB material is assumed to be 1.6mm thick FR4 with a dielectric constant of 4.3. Two situations are considered; one with no ground plane and one with a ground plane on the bottom of the board, underneath the RF connector. In both cases there is no inner layer tracking under the RF connector.

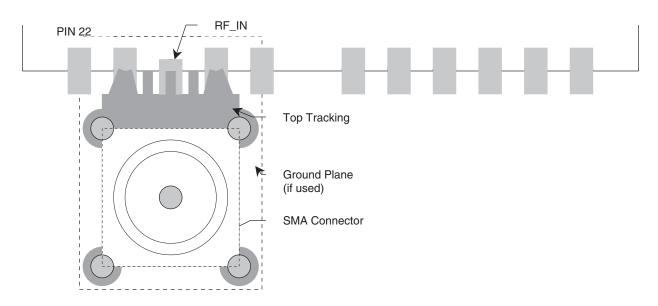


Figure 7 RF Tracking Example



8 APPLICATION HINTS continued

The widths of the RF_IN track and the associated gaps are given in the table below.

Scenario	Track Width (1/1000 Inch)	Gap Width (1/1000 Inch)	
Without ground plane	37	6	
	56	8	
With ground plane	32	6	
	43	8	

Table 7 RF Track & Gap Widths

Alternatively, the user can attach the antenna to the Hirose H.FL-R-SMT using a flying lead fitted with a suitable plug.

8.3 Grounding

In connecting the Wi125 into a host system, good grounding practices should be observed. Specifically, ground currents from the rest of the system hosting the Wi125 should not pass through the ground connections to the Wi125 . This is most easily ensured by using a single point attachment for the ground. There must also be a good connection between the RF_GND and the DIG_GND signals. While there is not a specific need to put a ground plane under the Wi125 , high energy signals should not be tracked under the Wi125 . It is however recommended that a ground plane be used under the Wi125 . In this case, the following would be an example of the pattern that may be used

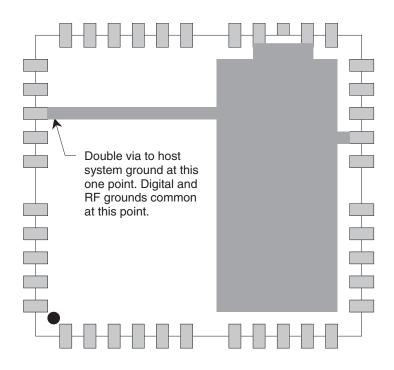


Figure 8 Grounding the Wi125 with a Ground Plane



8 APPLICATION HINTS continued

8.4 Battery Backup

The Wi125 has an on-board real time clock (RTC). This is used to store date and time information while the Wi125 is powered down. Having a valid date and time speeds the Time To First Fix (TTFF), allowing the Wi125 to meet its quoted TTFF specification. The Wi125 relies on an external power source to power the RTC (VBATT) when the DIG_3V3 is not present. If the user application does not require the warm or hot fix performance, or the required information is provided by network assistance, there is no need to provide the VBATT signal. The VBATT signal must be greater than 2.6V and less than DIG_3V3 + 0.6V. Typically, a 3V lithium primary cell or a high capacity "supercap" will be used. The Wi125 has an internal blocking diode, so if a "supercap" or rechargeable battery is used, an external charging circuit will be required.

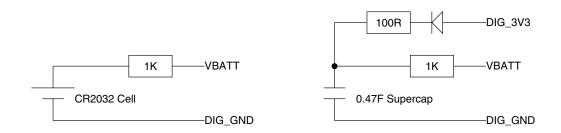


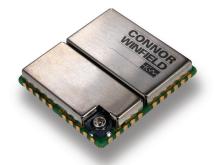
Figure 7 Typical VBATT Supplies





125 Series Wi125 Series





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